

MH257ESN Hall-effect sensor is a temperature stable, stress-resistant, Low Tolerance of Sensitivity micro-power switch. Superior high-temperature performance is made possible through a dynamic offset cancellation that utilizes chopper-stabilization. This method reduces the offset voltage normally caused by device over molding, temperature dependencies, and thermal stress.

MH257ESN is special made for low operation voltage, 1.65V, to active the chip which is includes the following on a single silicon chip: voltage regulator, Hall voltage generator, small-signal amplifier, chopper stabilization, Schmitt trigger, CMOS output driver. Advanced CMOS wafer fabrication processing is used to take advantage of low-voltage requirements, component matching, very low input-offset errors, and small component geometries. This device requires the presence of unipolar magnetic fields for operation.

The package type is in a Halogen Free version has been verified by third party Lab.

Features and Benefits

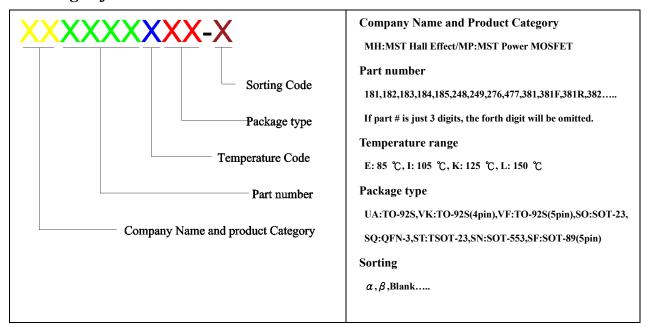
- CMOS Hall IC Technology
- 1.70 to 5.5V for battery-powered applications
- Omni polar, output switches with absolute value of North pole from magnet
- Operation down to 1.70V, Micro power consumption
- High Sensitivity for reed switch replacement applications
- Two Small Size option
- Low sensitivity drift in crossing of Temp range
- Low power consumption at 5uA (Avg)
- High ESD Protection, HBM $> \pm 4$ KV(min)
- Totem-pole output
- RoHS compliant 2011/65/EU and Halogen Free

Applications

- Solid state switch
- Handheld Wireless Handset Awake Switch (Flip Cell/PHS Phone/Note Book/Flip Video Set)
- Magnet proximity sensor for reed switch replacement in low duty cycle applications
- Water Meter
- PDA
- PDVD
- NB
- Pad PC



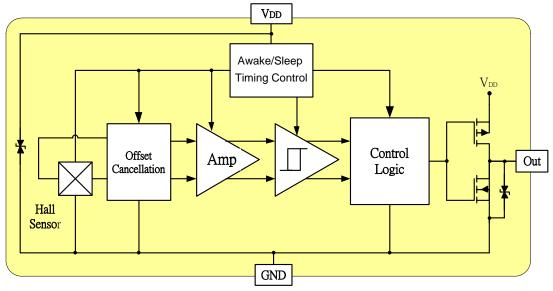
Ordering Information



Part No.	Temperature Suffix	Package Type	
MH257ESN	E $(-40^{\circ}\text{C to} + 85^{\circ}\text{C})$	SN (SOT-553)	

Custom sensitivity selection is available by MST sorting technology

Functional Diagram



Note: Static sensitive device; please observe ESD precautions. Reverse V_{DD} protection is not included. For reverse voltage protection, a 100Ω resistor in series with V_{DD} is recommended.

MH257, $HBM > \pm 4KV$ which is verified by third party lab.



Absolute Maximum Ratings At(Ta=25 °C)

Characteris	Values	Unit	
Supply voltage,(VDD)	6	V	
Output Voltage,(Vout)	6	V	
Reverse Voltage, (V_{DD}) (V_{OUT})	-0.3	V	
Magnetic flux density		Unlimited	Gauss
Output current,(Iovr)		1	mA
Operating temperature range, (Ta)		-40 to +85	$^{\circ}\mathbb{C}$
Storage temperature range, (<i>Ts</i>)		-65 to +150	$^{\circ}\mathbb{C}$
Maximum Junction Temp,(<i>Tj</i>)		150	$^{\circ}$ C
Thermal Resistance	$(\theta_{\scriptscriptstyle JA})$ SN	540	°C/W
Thermal Resistance	(θ_{JC}) SN	390	°C/W
Package Power Dissipation, (P_D) SN		230	mW

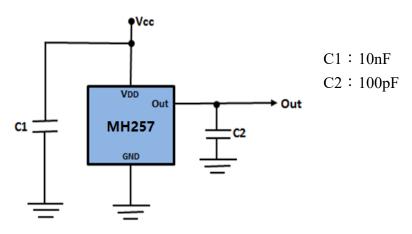
Note: Exceeding the absolute maximum ratings may cause permanent damage. Exposure to absolute maximum-rated conditions for extended periods may affect device reliability.

Electrical Specifications

DC Operating Parameters : Ta=25°C, $V_{DD}=2.0V$

Parameters Parameters		Test Conditions	Min	Тур	Max	Units
Supply Voltage,(VDD)		Operating	1.7		5.5	Volts
Supply Current,(IDD)		Awake State		1.5	3	mA
		Sleep State		3.5	7	μΑ
		Average		5	10	μΑ
Output Leakage Current,(Ioff)		Output off			1	uA
Output High Voltage,(Voн)		Iout=0.5mA(Source)	V _{DD} -0.2			V
Output Low Voltage,(Vol)		Iout=0.5mA(Sink)			0.2	V
Awake mode time,(<i>Taw</i>)		Operating		40	80	uS
Sleep mode time, (T_{SL})		Operating		40	80	mS
Duty Cycle,(D,C)				0.1		%
Electro-Static Discharge		HBM	4			KV
Operating Point	B _{OP}	N pole to branded side, B > BOP, Vout On	-50	-30		Gauss
Release Point	B _{RP}	N pole to branded side, B < BRP, Vout Off		-20	-10	Gauss
Hysteresis	B _{HY}	BOPx - BRPx		10		Gauss

Typical application circuit

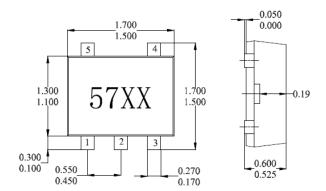


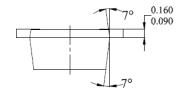


Sensor Location, package dimension and marking

SN Package (SOT-553)

(Top View)





NOTES:

1. PINOUT (See Top View at left:)

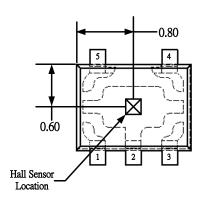
Pin 1 NC; Pin 2 GND

Pin 3 NC; Pin 4 VDD

Pin 5 Out

2. Controlling dimension: mm;

Hall Plate Chip Location (Top View)



(For reference only)Land Pattern

